




## Insulated Gate Bipolar Transistor (Ultrafast IGBT), 75 A



SOT-227

### FEATURES

- NPT Generation V IGBT technology
- Square RBSOA
- HEXFRED® low  $Q_{rr}$ , low switching energy
- Positive  $V_{CE(on)}$  temperature coefficient
- Fully isolated package
- Speed 8 kHz to 60 kHz
- Very low internal inductance ( $\leq 5$  nH typical)
- Industry standard outline
- UL approved file E78996 
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



RoHS  
COMPLIANT

PRODUCT SUMMARY	
$V_{CES}$	1200 V
$I_C$ DC	75 A at 95 °C
$V_{CE(on)}$ typical at 75 A, 25 °C	3.3 V
Package	SOT-227

### BENEFITS

- Designed for increased operating efficiency in power conversion: UPS, SMPS, welding, induction heating
- Easy to assemble and parallel
- Direct mounting on heatsink
- Plug-in compatible with other SOT-227 packages
- Low EMI, requires less snubbing

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	$V_{CES}$		1200	V
Continuous collector current	$I_C$	$T_C = 25\text{ °C}$	131	A
		$T_C = 80\text{ °C}$	89	
Pulsed collector current	$I_{CM}$		200	
Clamped inductive load current	$I_{LM}$		200	
Diode continuous forward current	$I_F$	$T_C = 25\text{ °C}$	59	
		$T_C = 80\text{ °C}$	39	
Gate to emitter voltage	$V_{GE}$		$\pm 20$	V
Power dissipation, IGBT	$P_D$	$T_C = 25\text{ °C}$	658	W
		$T_C = 80\text{ °C}$	369	
Power dissipation, diode	$P_D$	$T_C = 25\text{ °C}$	240	
		$T_C = 80\text{ °C}$	135	
Isolation voltage	$V_{ISOL}$	Any terminal to case, $t = 1$ min	2500	V



ELECTRICAL SPECIFICATIONS (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	V <sub>BR(CES)</sub>	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 250 μA	1200	-	-	V
Collector to emitter voltage	V <sub>CE(on)</sub>	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 75 A	-	3.3	3.8	
		V <sub>GE</sub> = 15 V, I <sub>C</sub> = 75 A, T <sub>J</sub> = 125 °C	-	3.6	3.9	
Gate threshold voltage	V <sub>GE(th)</sub>	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 250 μA	4	5	6	
Temperature coefficient of threshold voltage	V <sub>GE(th)</sub> /ΔT <sub>J</sub>	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 1 mA (25 °C to 125 °C)	-	- 12	-	mV/°C
Collector to emitter leakage current	I <sub>CES</sub>	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V	-	3	250	μA
		V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V, T <sub>J</sub> = 150 °C	-	4	20	mA
Forward voltage drop	V <sub>FM</sub>	I <sub>C</sub> = 75 A, V <sub>GE</sub> = 0 V	-	3.4	5.0	V
		I <sub>C</sub> = 75 A, V <sub>GE</sub> = 0 V, T <sub>J</sub> = 125 °C	-	3.3	5.2	
Gate to emitter leakage current	I <sub>GES</sub>	V <sub>GE</sub> = ± 20 V	-	-	± 200	nA

SWITCHING CHARACTERISTICS (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Total gate charge (turn-on)	Q <sub>g</sub>	I <sub>C</sub> = 50 A, V <sub>CC</sub> = 600 V, V <sub>GE</sub> = 15 V		-	690	-	nC
Gate to emitter charge (turn-on)	Q <sub>ge</sub>			-	65	-	
Gate to collector charge (turn-on)	Q <sub>gc</sub>			-	250	-	
Turn-on switching loss	E <sub>on</sub>	I <sub>C</sub> = 75 A, V <sub>CC</sub> = 600 V, V <sub>GE</sub> = 15 V, R <sub>g</sub> = 5 Ω, L = 500 μH, T <sub>J</sub> = 25 °C	Energy losses include tail and diode recovery (see fig. 18)	-	1.53	-	mJ
Turn-off switching loss	E <sub>off</sub>			-	1.76	-	
Total switching loss	E <sub>tot</sub>			-	3.29	-	
Turn-on switching loss	E <sub>on</sub>			-	2.49	-	
Turn-off switching loss	E <sub>off</sub>			-	3.45	-	
Total switching loss	E <sub>tot</sub>			-	5.94	-	
Turn-on delay time	t <sub>d(on)</sub>	I <sub>C</sub> = 75 A, V <sub>CC</sub> = 600 V, V <sub>GE</sub> = 15 V, R <sub>g</sub> = 5 Ω, L = 500 μH, T <sub>J</sub> = 125 °C		-	281	-	ns
Rise time	t <sub>r</sub>			-	45	-	
Turn-off delay time	t <sub>d(off)</sub>			-	300	-	
Fall time	t <sub>f</sub>			-	126	-	
Reverse bias safe operating area	RBSOA	T <sub>J</sub> = 150 °C, I <sub>C</sub> = 200 A, R <sub>g</sub> = 22 Ω, V <sub>GE</sub> = 15 V to 0 V, V <sub>CC</sub> = 900 V, V <sub>P</sub> = 1200 V, L = 500 μH		Fullsquare			
Diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 50 A, dI <sub>F</sub> /dt = 200 A/μs, V <sub>R</sub> = 200 V		-	142	210	ns
Diode peak reverse current	I <sub>rr</sub>			-	13	16	A
Diode recovery charge	Q <sub>rr</sub>			-	923	1680	nC
Diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 50 A, dI <sub>F</sub> /dt = 200 A/μs, V <sub>R</sub> = 200 V, T <sub>J</sub> = 125 °C		-	202	260	ns
Diode peak reverse current	I <sub>rr</sub>			-	18	22	A
Diode recovery charge	Q <sub>rr</sub>			-	1818	2860	nC



THERMAL AND MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL		MIN.	TYP.	MAX.	UNITS	
Junction and storage temperature range	$T_J, T_{Stg}$		- 40	-	150	°C	
Junction to case	IGBT	$R_{thJC}$	-	-	0.19	°C/W	
	Diode		-	-	0.52		
Case to heatsink	$R_{thCS}$		-	0.05	-		
Weight			-	30	-	g	
Mounting torque			-	-	1.3	Nm	
Case style	SOT-227						

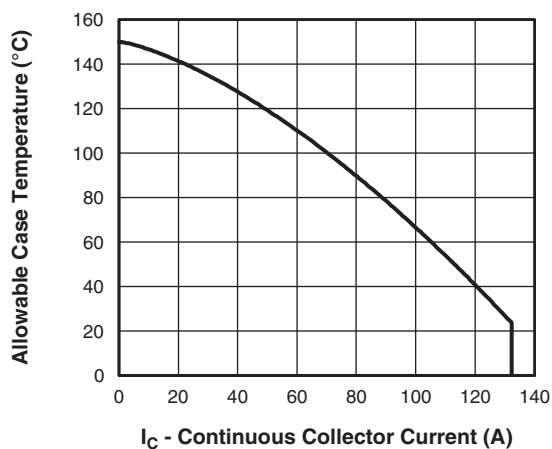


Fig. 1 - Maximum DC IGBT Collector Current vs. Case Temperature

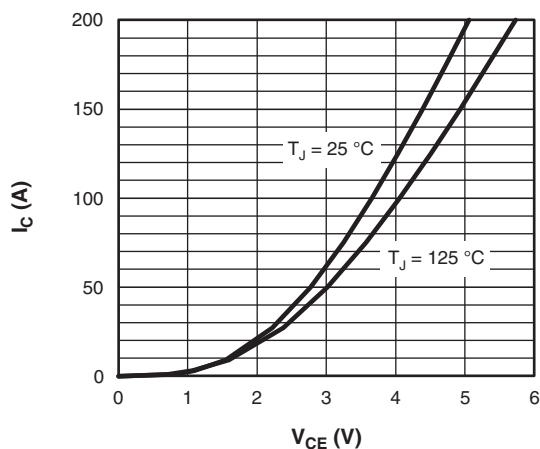


Fig. 3 - Typical IGBT Collector Current Characteristics

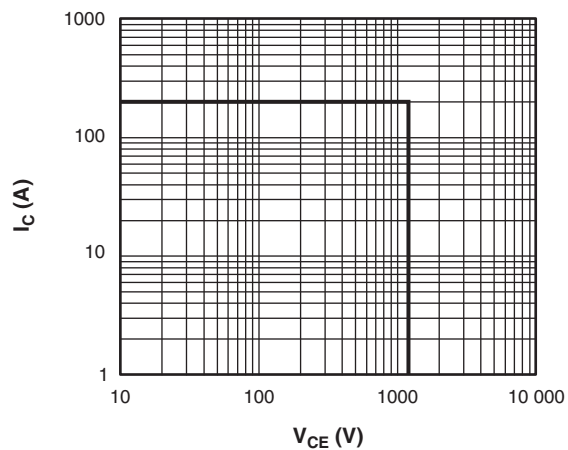


Fig. 2 - IGBT Reverse Bias SOA  
 $T_J = 150^\circ\text{C}, V_{GE} = 15\text{ V}$

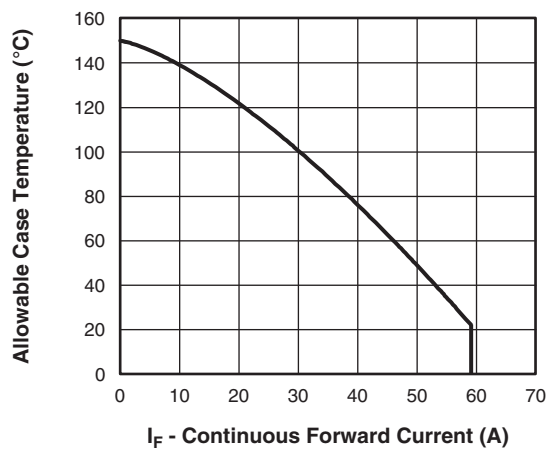


Fig. 4 - Maximum DC Forward Current vs. Case Temperature

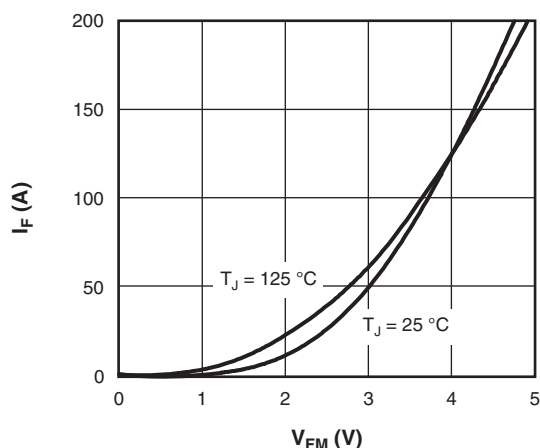


Fig. 5 - Typical Diode Forward Characteristics

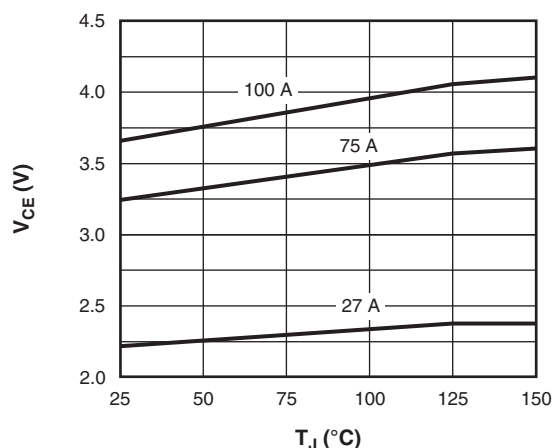


Fig. 8 - Typical IGBT Collector to Emitter Voltage vs. Junction Temperature,  $V_{GE} = 15\text{ V}$

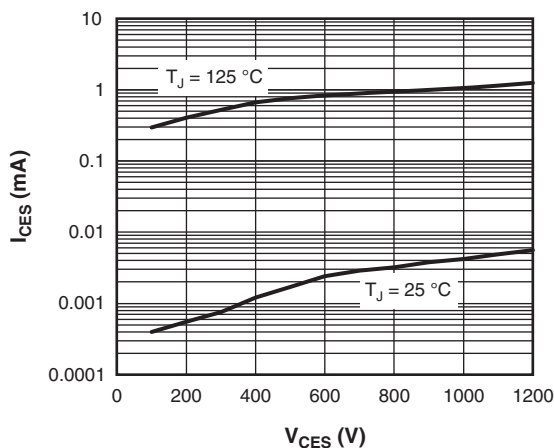


Fig. 6 - Typical IGBT Zero Gate Voltage Collector Current

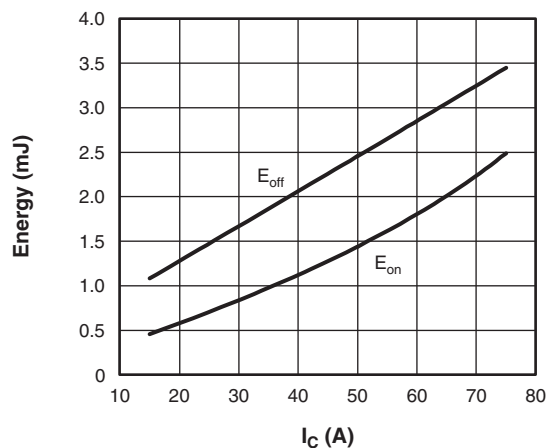


Fig. 9 - Typical IGBT Energy Loss vs.  $I_C$   
 $T_J = 125\text{ °C}$ ,  $L = 500\text{ }\mu\text{H}$ ,  $V_{CC} = 600\text{ V}$ ,  
 $R_g = 5\text{ }\Omega$ ,  $V_{GE} = 15\text{ V}$

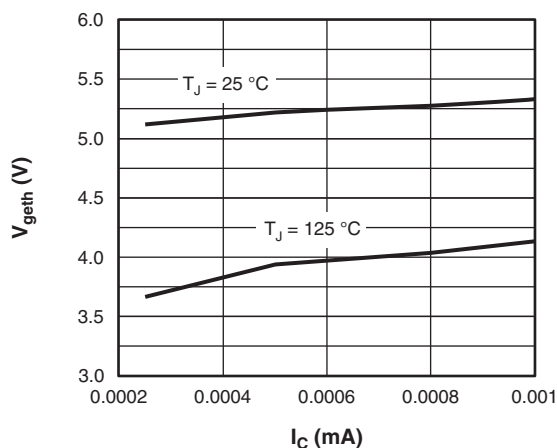


Fig. 7 - Typical IGBT Threshold Voltage

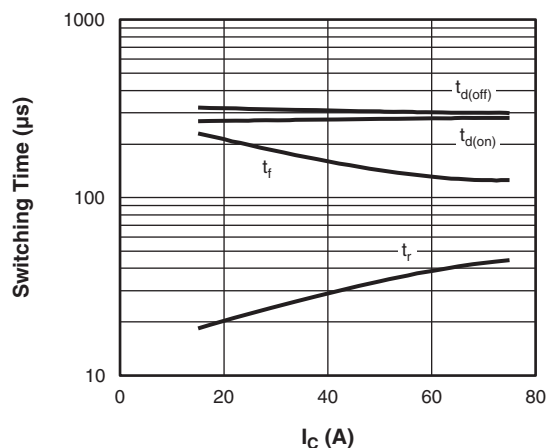


Fig. 10 - Typical IGBT Switching Time vs.  $I_C$   
 $T_J = 125\text{ °C}$ ,  $L = 500\text{ }\mu\text{H}$ ,  $V_{CC} = 600\text{ V}$ ,  
 $R_g = 5\text{ }\Omega$ ,  $V_{GE} = 15\text{ V}$

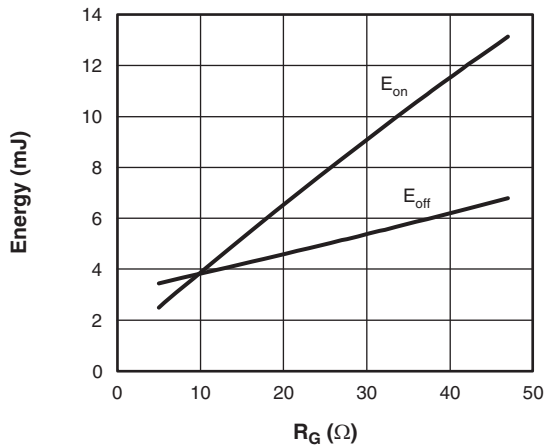


Fig. 11 - Typical IGBT Energy Loss vs.  $R_g$   
 $T_J = 125\text{ }^\circ\text{C}$ ,  $I_C = 75\text{ A}$ ,  $L = 500\text{ }\mu\text{H}$ ,  
 $V_{CC} = 600\text{ V}$ ,  $V_{GE} = 15\text{ V}$

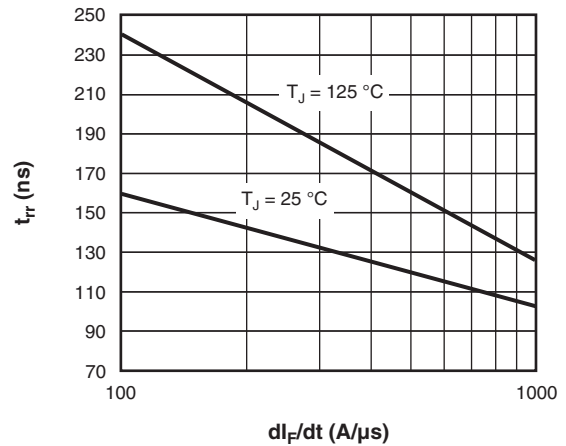


Fig. 13 - Typical  $t_{rr}$  diode vs.  $dI_F/dt$   
 $V_{RR} = 200\text{ V}$ ,  $I_F = 50\text{ A}$

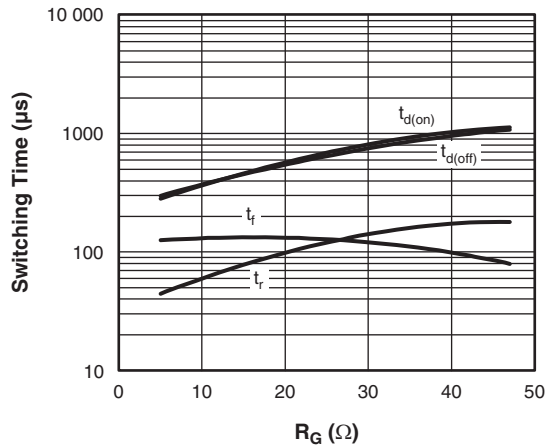


Fig. 12 - Typical IGBT Switching Time vs.  $R_g$   
 $T_J = 125\text{ }^\circ\text{C}$ ,  $L = 500\text{ }\mu\text{H}$ ,  $V_{CC} = 600\text{ V}$ ,  
 $R_g = 5\text{ }\Omega$ ,  $V_{GE} = 15\text{ V}$

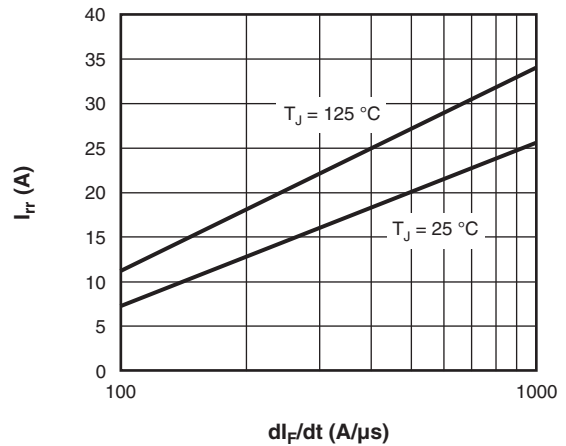


Fig. 14 - Typical  $I_{rr}$  diode vs.  $dI_F/dt$   
 $V_{RR} = 200\text{ V}$ ,  $I_F = 50\text{ A}$

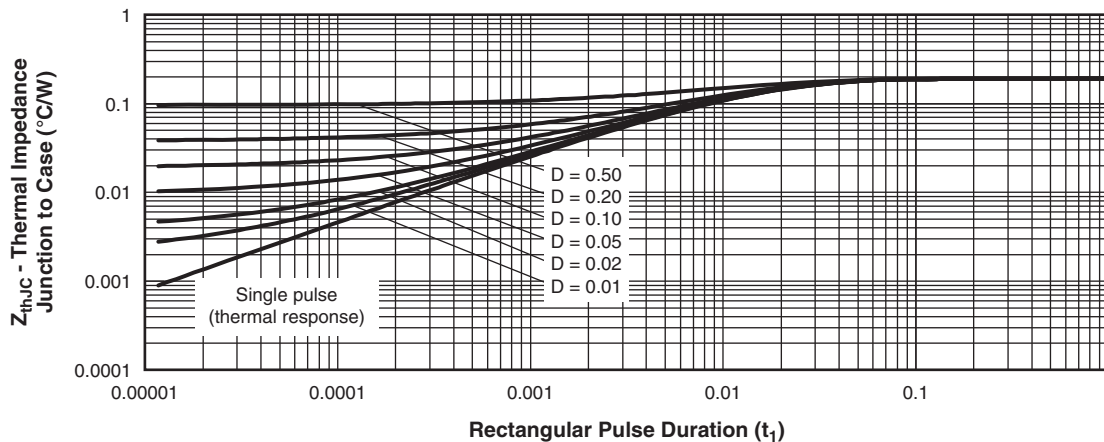


Fig. 15 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (IGBT)

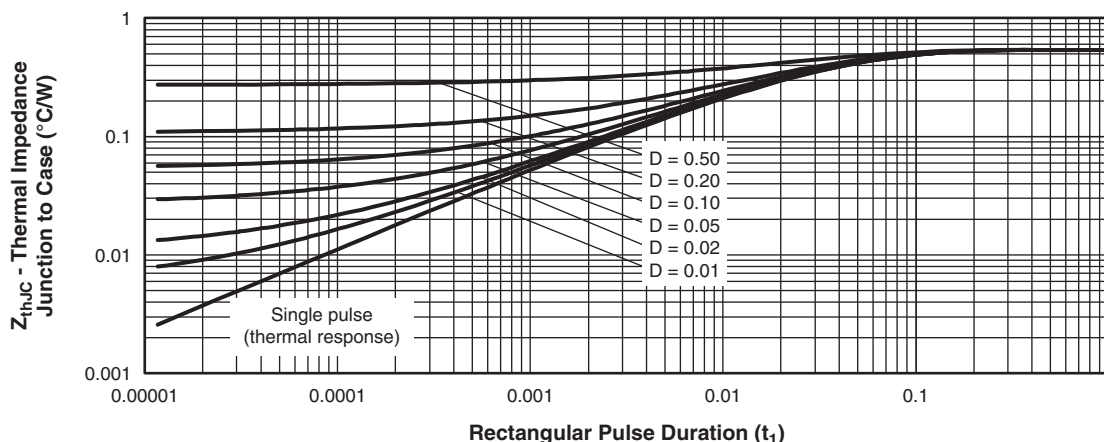
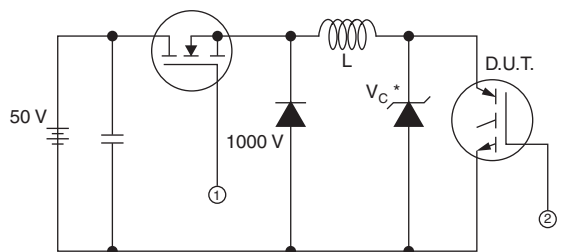


Fig. 16 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (diode)



\* Driver same type as D.U.T.;  $V_C = 80\%$  of  $V_{ce(max)}$   
\* Note: Due to the 50 V power supply, pulse width and inductor will increase to obtain  $I_d$

Fig. 17a - Clamped Inductive Load Test Circuit

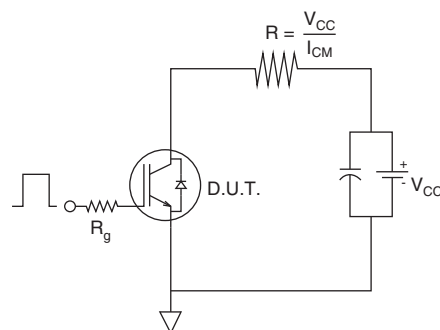


Fig. 17b - Pulsed Collector Current Test Circuit

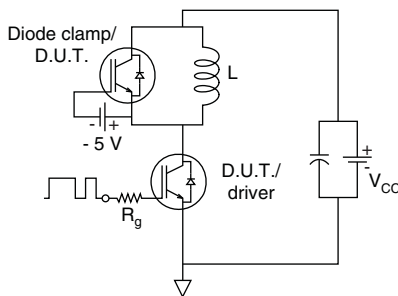


Fig. 18a - Switching Loss Test Circuit

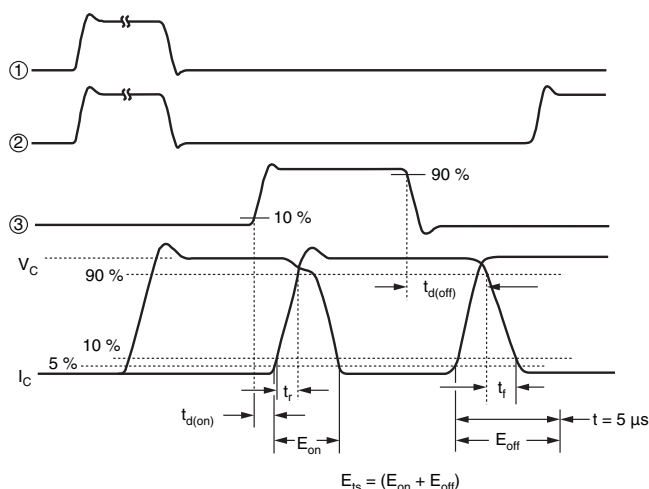


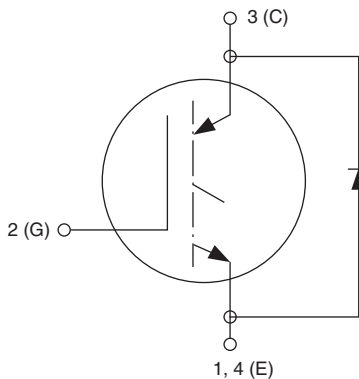
Fig. 18b - Switching Loss Waveforms Test Circuit

**ORDERING INFORMATION TABLE**

Device code	<b>VS-</b>	<b>G</b>	<b>B</b>	<b>75</b>	<b>D</b>	<b>A</b>	<b>120</b>	<b>U</b>	<b>P</b>
	①	②	③	④	⑤	⑥	⑦	⑧	⑨

- 1** - Vishay Semiconductors product
- 2** - Insulated Gate Bipolar Transistor (IGBT)
- 3** - B = IGBT Generation 5
- 4** - Current rating (75 = 75 A)
- 5** - Circuit configuration (D = Single switch with antiparallel diode)
- 6** - Package indicator (A = SOT-227)
- 7** - Voltage rating (120 = 1200 V)
- 8** - Speed/type (U = Ultrafast IGBT)
- 9** - Totally lead (Pb)-free

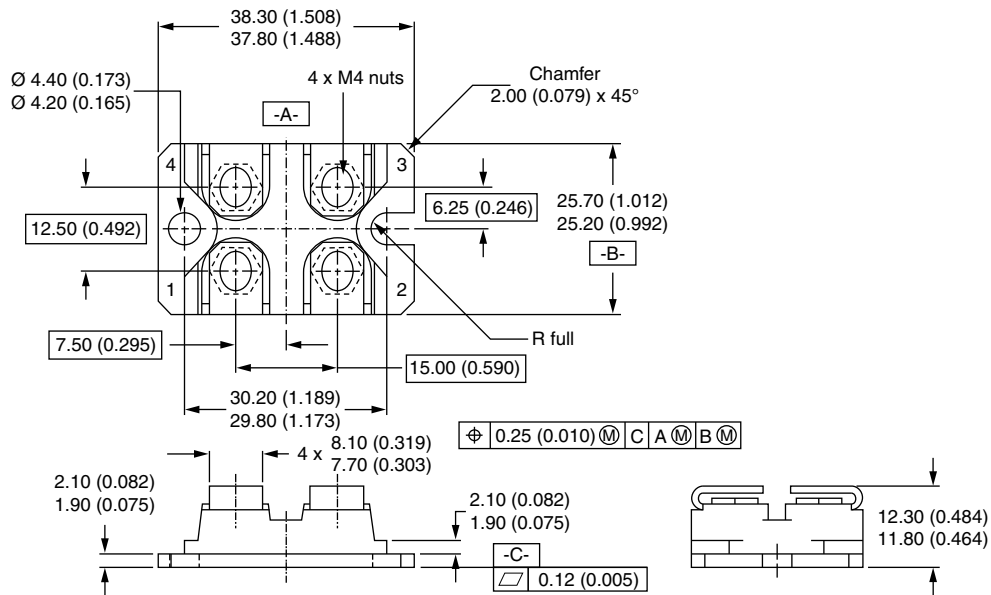
**CIRCUIT CONFIGURATION**



LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95036">www.vishay.com/doc?95036</a>
Packaging information	<a href="http://www.vishay.com/doc?95037">www.vishay.com/doc?95037</a>

## SOT-227

**DIMENSIONS** in millimeters (inches)



### Notes

- Dimensioning and tolerancing per ANSI Y14.5M-1982
- Controlling dimension: millimeter





## Disclaimer

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